Qualcomm

RF360
Europe GmbH

Data sheet

E-Duplexer
Small cell
LTE band 3

Series/type:	D7906
Ordering code:	B39182D7906D310
Date:	July 27, 2018
Version:	2.0

RF360 products mentioned within this document are products of RF360 Europe GmbH and other subsidiaries of RF360 Holdings Singapore Pte. Ltd. (collectively, the “RF360 Subsidiaries”).

RF360 Europe GmbH, Anzinger Str. 13, München, Germany

RF360 Europe GmbH

A Qualcomm – TDK Joint Venture

Data sheet

E-Duplexer

Small cell
LTE band 3

Series/type:	D7906
Ordering code:	B39182D7906D310
Date:	July 27, 2018
Version:	2.0

Table of contents

1 Application....4
2 Features....4
3 Package....5
4 Pin configuration....6
5 Matching circuit....7
6 Characteristics....8
7 Maximum ratings....14
8 Transmission coefficients....15
9 Reflection coefficients....18
10 EVMs....19
11 Packing material....21
12 Marking....24
13 Soldering profile....26
14 Annotations....27
15 Cautions and warnings....28
16 Important notes....29

1 Application

- Enhanced duplexer for LTE small cell systems (Band 3)
- Low VSWR
- Usable pass band 75 MHz
- Rx = uplink = 1710 MHz – 1785 MHz
- Tx = downlink = 1805 MHz – 1880 MHz

2 Features

- Package size 8.1±0.1 mm × 8.1±0.1 mm
- Package height 1.1 mm (max.)
- Approximate weight 0.2 g
- RoHS compatible
- Package for Surface Mount Technology (SMT)
- Ni/Au-plated terminals
- Electrostatic Sensitive Device (ESD)
- Moisture Sensitivity Level 3 (MSL3)

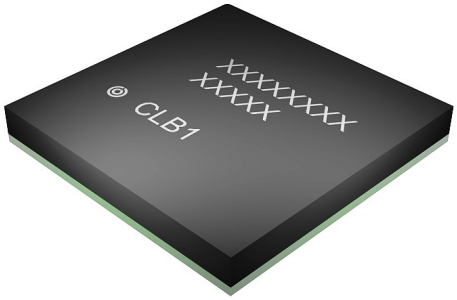

Figure 1: Picture of component with example of product marking.

3 Package

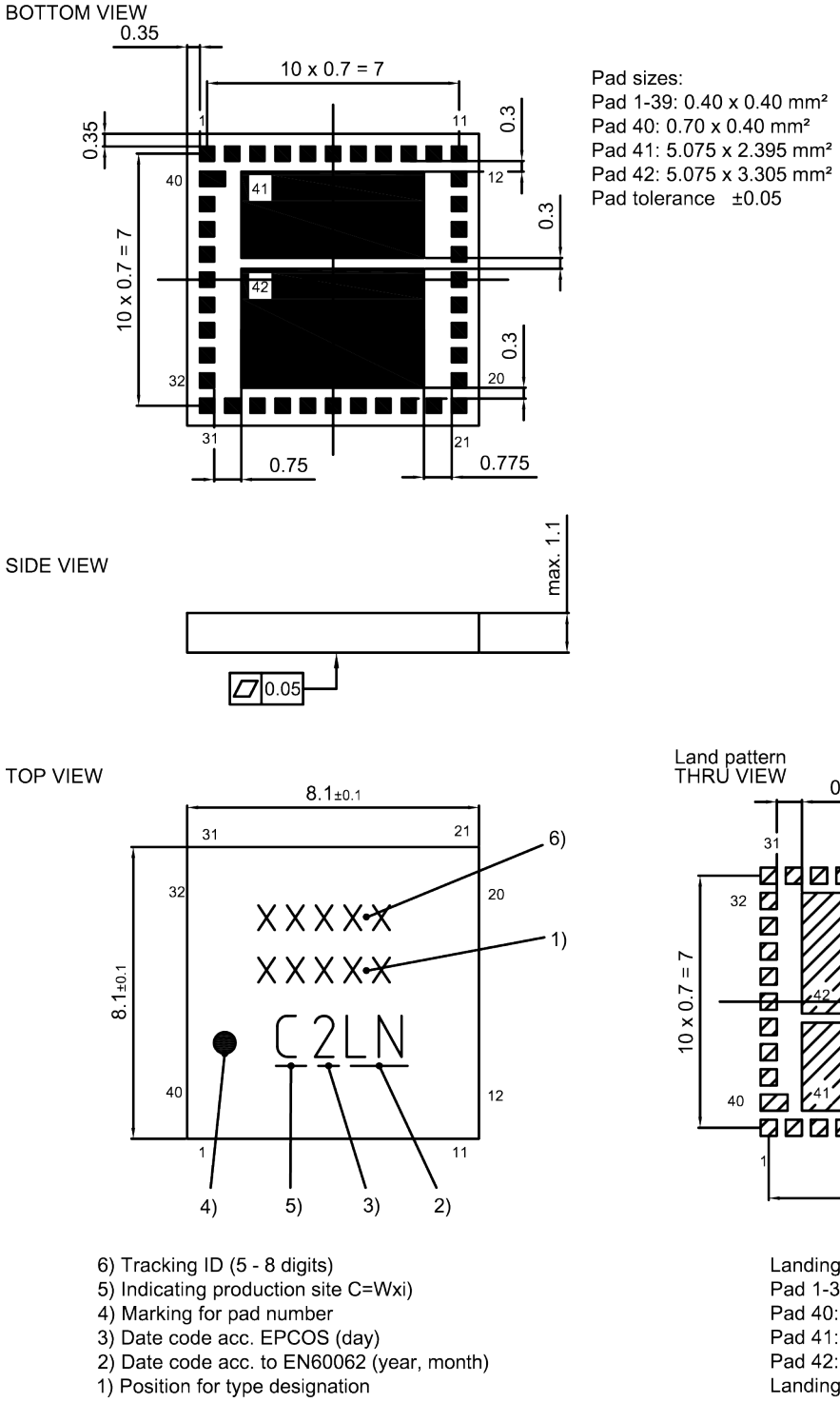

Figure 2: Drawing of package with package height A = 1.1 mm (max.). See Sec. Package information (p. 28).

4 Pin configuration

- 3 TX
- 13 RX
- 29 ANT
- 1, 2, 4, 5, 6, 7, 8, 9, 10, 11, 12, 14, 15, 16, 17, 18, 19, 20, 21, 22, 23, 24, 25, 26, 27, 28, 30, 31, 32, 33, 34, 35, 36, 37, 38, 39, 40, 41, 42 Ground

5 Matching circuit

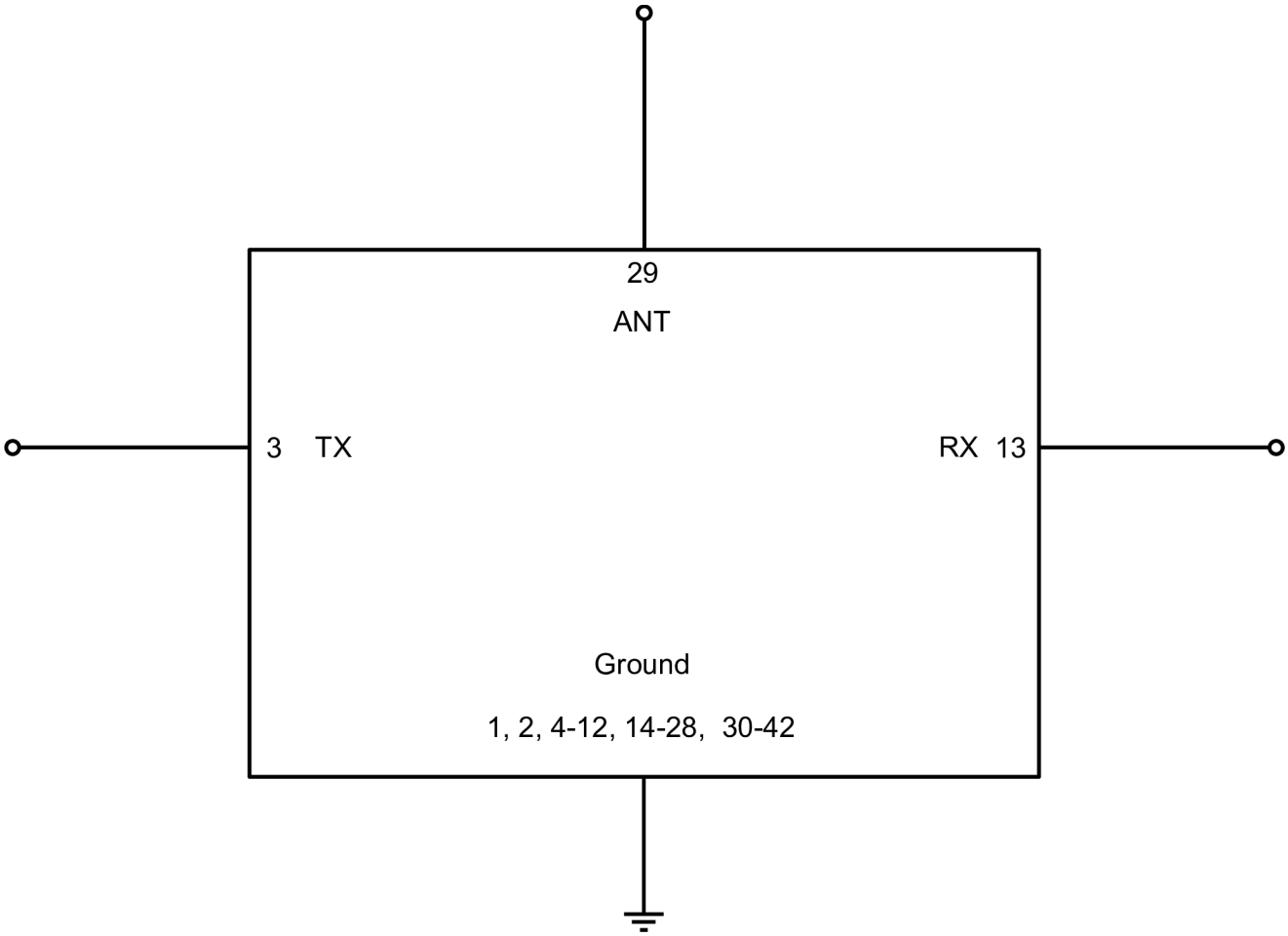

Figure 3: Schematic of matching circuit. No external matching components required.

6 Characteristics

6.1 TX – ANT

Temperature range for specification T_{SPEC} = −10 °C ... +85 °C
TX terminating impedance Z_{TX} = 50 Ω
ANT terminating impedance Z_{ANT} = 50 Ω
RX terminating impedance Z_{RX} = 50 Ω

Characteristics TX – ANT				min. for T_{SPEC}	typ. @ +25 °C	max. for T_{SPEC}	
Center frequency			f_C	—	1842.5	—	MHz
Average insertion attenuation			$\alpha_{INT,avg}$ [1]				
	1805... 1810	MHz		—	3.3	4.2	dB
	1810... 1875	MHz		—	3.1	3.8	dB
	1875... 1880	MHz		—	3.0	3.8	dB
Maximum insertion attenuation			α_{max}				
	1805.24... 1879.76	MHz		—	3.6	5.0	dB
	1810... 1875	MHz		—	3.3	4.0	dB
Amplitude ripple (p-p)			$\Delta\alpha$				
	1805.24... 1879.76	MHz		—	1.6	3.2	dB
Maximum VSWR			$VSWR_{max}$				
@ TX port	1805.24... 1879.76	MHz		—	1.3	1.7	
@ ANT port	1805.24... 1879.76	MHz		—	1.2	1.4	
Maximum error vector magnitude			EVM_{max} [2]				
	1807.4... 1877.6	MHz		—	1.5	4.0	%
Minimum attenuation			α_{min}				
	10... 1710	MHz		30	38	—	dB
	1710.24... 1745	MHz		42	50	—	dB
	1745... 1775	MHz		45	53	—	dB
	1775... 1780	MHz		42	50	—	dB
	1780... 1784.76	MHz		35	45	—	dB
	1900... 1911	MHz		6	20	—	dB
	1911... 1920	MHz		35	59	—	dB
	1920... 1980	MHz		40	51	—	dB
	1980... 2500	MHz		35	45	—	dB
	2500... 3740	MHz		35	47	—	dB
	3740... 5150	MHz		30	42	—	dB
	5150... 5725	MHz		30	42	—	dB

[1] Integrated attenuation α_{INT}: Averaged power $|S_{ij}|^2$ over the center 4.5 MHz of LTE 5 MHz (25 RB) channels.
[2] Error Vector Magnitude (EVM) based on definition in 3GPP TS 25.141.

Temperature range for specification	T_{SPEC}	= −40 °C ... +95 °C
TX terminating impedance	Z_{TX}	= 50 Ω
ANT terminating impedance	Z_{ANT}	= 50 Ω
RX terminating impedance	Z_{RX}	= 50 Ω

Characteristics TX – ANT				**min.** for T_{SPEC}	**typ.** @ +25 °C	**max.** for T_{SPEC}	
Average insertion attenuation			$\alpha_{INT,avg}$ [1]				
	1805 ... 1810	MHz		—	3.3	4.7	dB
	1810 ... 1875	MHz		—	3.1	4.0	dB
	1875 ... 1880	MHz		—	3.0	4.0	dB
Maximum insertion attenuation			α_{max}				
	1805.24 ... 1879.76	MHz		—	3.6	6.0	dB
	1810 ... 1875	MHz		—	3.3	5.0	dB
Amplitude ripple (p-p)			$\Delta\alpha$				
	1805.24 ... 1879.76	MHz		—	1.6	4.5	dB
Maximum VSWR			$VSWR_{max}$				
@ TX port	1805.24 ... 1879.76	MHz		—	1.3	1.7	
@ ANT port	1805.24 ... 1879.76	MHz		—	1.2	1.7	
Maximum error vector magnitude			EVM_{max} [2]				
	1807.4 ... 1877.6	MHz		—	1.5	5.7	%
Minimum attenuation			α_{min}				
	10 ... 1710	MHz		30	38	—	dB
	1710.24 ... 1745	MHz		42	50	—	dB
	1745 ... 1775	MHz		45	53	—	dB
	1775 ... 1780	MHz		42	50	—	dB
	1780 ... 1784.76	MHz		30	45	—	dB
	1900 ... 1911	MHz		4	20	—	dB
	1911 ... 1920	MHz		28	59	—	dB
	1920 ... 1980	MHz		40	51	—	dB
	1980 ... 2500	MHz		35	45	—	dB
	2500 ... 3740	MHz		35	47	—	dB
	3740 ... 5150	MHz		30	42	—	dB
	5150 ... 5725	MHz		30	42	—	dB

[1] Integrated attenuation α_{INT}: Averaged power $|S_{ij}|^2$ over the center 4.5 MHz of LTE 5 MHz (25 RB) channels.

[2] Error Vector Magnitude (EVM) based on definition in 3GPP TS 25.141.

6.2 ANT – RX

Temperature range for specification	T_{SPEC}	= −10 °C ... +85 °C
TX terminating impedance	Z_{TX}	= 50 Ω
ANT terminating impedance	Z_{ANT}	= 50 Ω
RX terminating impedance	Z_{RX}	= 50 Ω

Characteristics ANT – RX				**min.** for T_{SPEC}	**typ.** @ +25 °C	**max.** for T_{SPEC}	
Center frequency			f_C	—	1747.5	—	MHz
Average insertion attenuation			$\alpha_{INT,avg}$ [1]				
	1710... 1715	MHz		—	3.5	5.0	dB
	1715... 1780	MHz		—	4.0	5.5	dB
	1780... 1785	MHz		—	4.4	6.3	dB
Maximum insertion attenuation			α_{max}				
	1710.24... 1784.76	MHz		—	4.7	7.2	dB
	1715... 1775	MHz		—	3.6	4.6	dB
Amplitude ripple (p-p)			$\Delta\alpha$				
	1710.24... 1784.76	MHz		—	2.3	4.5	dB
Maximum VSWR			$VSWR_{max}$				
@ ANT port	1710.24... 1784.76	MHz		—	1.3	1.5	
@ RX port	1710.24... 1784.76	MHz		—	1.5	1.7	
Maximum error vector magnitude			EVM_{max} [2]				
	1712.4... 1782.6	MHz		—	1.9	4.8	%
Minimum attenuation			α_{min}				
	10... 1660	MHz		40	50	—	dB
	1660... 1690	MHz		30	37	—	dB
	1805.24... 1840	MHz		40[3]	59	—	dB
	1840... 1879.76	MHz		45	60	—	dB
	1880... 2400	MHz		40	46	—	dB
	2400... 2500	MHz		40	51	—	dB
	2500... 3550	MHz		35	53	—	dB
	3550... 4200	MHz		35	47	—	dB
	4200... 5325	MHz		32	41	—	dB

[1] Integrated attenuation α_{INT}: Averaged power $|S_{ij}|^2$ over the center 4.5 MHz of LTE 5 MHz (25 RB) channels.
[2] Error Vector Magnitude (EVM) based on definition in 3GPP TS 25.141.
[3] Valid for temperature range +15 °C ... +85 °C.

Temperature range for specification	T_{SPEC}	= −40 °C ... +95 °C
TX terminating impedance	Z_{TX}	= 50 Ω
ANT terminating impedance	Z_{ANT}	= 50 Ω
RX terminating impedance	Z_{RX}	= 50 Ω

Characteristics ANT – RX				**min.** for T_{SPEC}	**typ.** @ +25 °C	**max.** for T_{SPEC}	
Average insertion attenuation			$\alpha_{INT,avg}$ [1]				
	1710... 1715	MHz		—	3.5	6.0	dB
	1715... 1780	MHz		—	4.0	6.0	dB
	1780... 1785	MHz		—	4.4	7.0	dB
Maximum insertion attenuation			α_{max}				
	1710.24... 1784.76	MHz		—	4.7	8.0	dB
	1715... 1775	MHz		—	3.6	5.5	dB
Amplitude ripple (p-p)			$\Delta\alpha$				
	1710.24... 1784.76	MHz		—	2.3	5.3	dB
Maximum VSWR			$VSWR_{max}$				
@ ANT port	1710.24... 1784.76	MHz		—	1.3	1.7	
@ RX port	1710.24... 1784.76	MHz		—	1.5	1.7	
Maximum error vector magnitude			EVM_{max} [2]				
	1712.4... 1782.6	MHz		—	1.9	7.8	%
Minimum attenuation			α_{min}				
	10... 1660	MHz		40	50	—	dB
	1660... 1690	MHz		25	37	—	dB
	1805.24... 1840	MHz		20	59	—	dB
	1840... 1879.76	MHz		45	60	—	dB
	1880... 2400	MHz		40	46	—	dB
	2400... 2500	MHz		40	51	—	dB
	2500... 3550	MHz		35	53	—	dB
	3550... 4200	MHz		35	47	—	dB
	4200... 5325	MHz		32	41	—	dB

[1] Integrated attenuation α_{INT}: Averaged power $|S_{ij}|^2$ over the center 4.5 MHz of LTE 5 MHz (25 RB) channels.

[2] Error Vector Magnitude (EVM) based on definition in 3GPP TS 25.141.

6.3 TX – RX

Temperature range for specification	T_{SPEC}	= −10 °C ... +85 °C
TX terminating impedance	Z_{TX}	= 50 Ω
ANT terminating impedance	Z_{ANT}	= 50 Ω
RX terminating impedance	Z_{RX}	= 50 Ω

Characteristics TX – RX				**min.** for T_{SPEC}	**typ.** @ +25 °C	**max.** for T_{SPEC}	
Average isolation			$\alpha_{INT,avg}$ [1]				
	1710... 1785	MHz		60	66	—	dB
	1805... 1815	MHz		60[2]	66	—	dB
	1815... 1880	MHz		60	66	—	dB
Minimum isolation			α_{min}				
	1710.24... 1784.76	MHz		60	66	—	dB
	1805.24... 1815	MHz		50[3]	67	—	dB
	1815... 1879.76	MHz		60	65	—	dB

1) Integrated attenuation α_{INT}: Averaged power $|S_{ij}|^2$ over the center 4.5 MHz of LTE 5 MHz (25 RB) channels.
2) Valid for temperature range +25 °C ... +85 °C. For −10°C...+25°C this value relaxes to 55 dB.
3) Valid for temperature range +25 °C ... +85 °C. For −10°C...+25°C this value relaxes to 40 dB.

Temperature range for specification	T_{SPEC}	= −40 °C ... +95 °C
TX terminating impedance	Z_{TX}	= 50 Ω
ANT terminating impedance	Z_{ANT}	= 50 Ω
RX terminating impedance	Z_{RX}	= 50 Ω

Characteristics TX – RX				**min.** for T_{SPEC}	**typ.** @ +25 °C	**max.** for T_{SPEC}	
Average isolation			$\alpha_{INT,avg}$ [1]				
	1710 ... 1785	MHz		60	66	—	dB
	1805 ... 1815	MHz		45	66	—	dB
	1815 ... 1880	MHz		60	66	—	dB
Minimum isolation			α_{min}				
	1710.24 ... 1784.76	MHz		55	66	—	dB
	1805.24 ... 1815	MHz		50 [2]	67	—	dB
	1815 ... 1879.76	MHz		60	65	—	dB

[1] Integrated attenuation α_{INT}: Averaged power $|S_{ij}|^2$ over the center 4.5 MHz of LTE 5 MHz (25 RB) channels.

[2] Valid for temperature range +25 °C ... +95 °C. For −40°C...+25°C this value relaxes to 35 dB.

7 Maximum ratings

Operable temperature	T_{OP} = −40 °C ... +95 °C	
Storage temperature	T_{STG} [1] = −40 °C ... +95 °C	
DC voltage	$\|V_{DC}\|$ [2] = 0 V	
ESD voltage		
	V_{ESD} [3] = 100 V	Machine model.
	V_{ESD} [4] = 100 V	Human body model.
Input power @ TX port: 1805.24 ... 1879.76 MHz	P_{IN} = 31 dBm [5, 6]	5 MHz LTE downlink signal for 100000 h @ 55 °C. P_{IN} average – 42 dBm peak. Source and load impedance 50Ω.

1) Not valid for packaging material. Storage temperature for packaging material is −25 °C to +40 °C.
2) In case of applied DC voltage blocking capacitors are mandatory.
3) According to JESD22-A115B (MM – Machine Model), 10 negative & 10 positive pulses.
4) According to JESD22-A114F (HBM – Human Body Model), 1 negative & 1 positive pulse.
5) Expected lifetime according to accelerated power durability tests, and wear out models.
6) T_{SPEC} is the ambient temperature of the PCB at component position. Specified min./max values from section 6 "characteristics" for maximum input power 28 dBm are valid for temperature up to 60 °C.

8 Transmission coefficients

8.1 TX – ANT

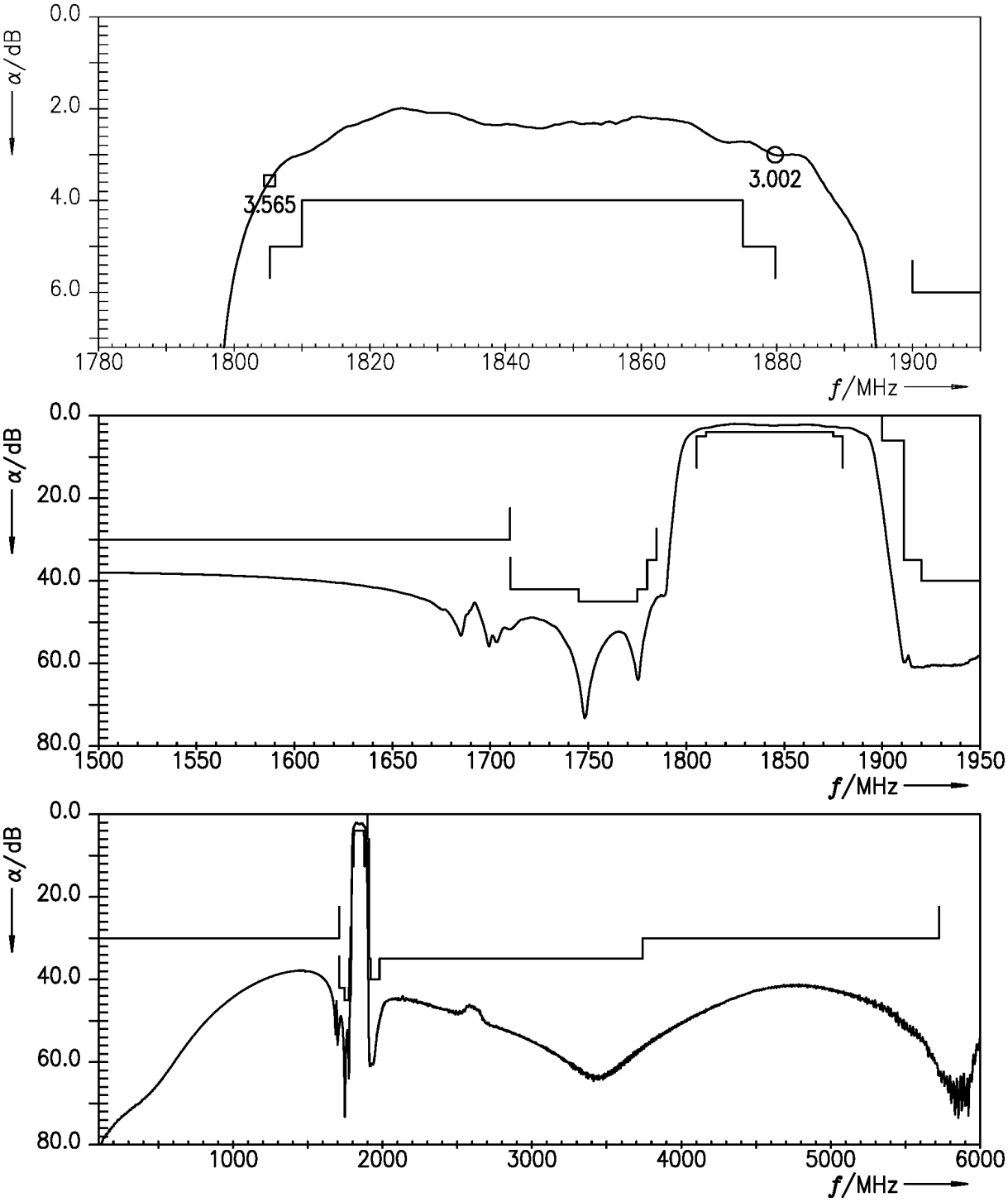

Figure 4: Attenuation TX – ANT.

8.2 ANT – RX

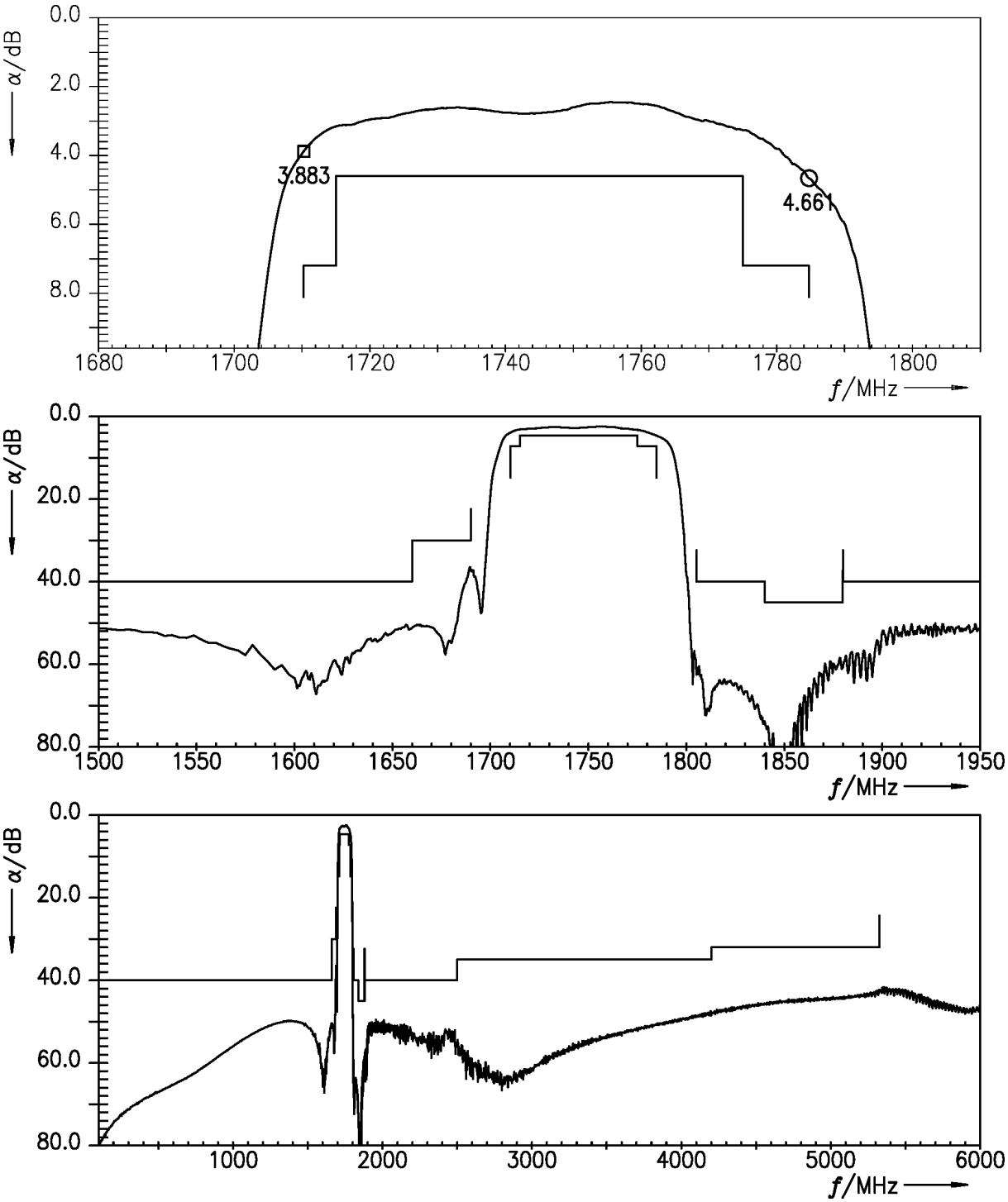

Figure 5: Attenuation ANT – RX.

8.3 TX – RX

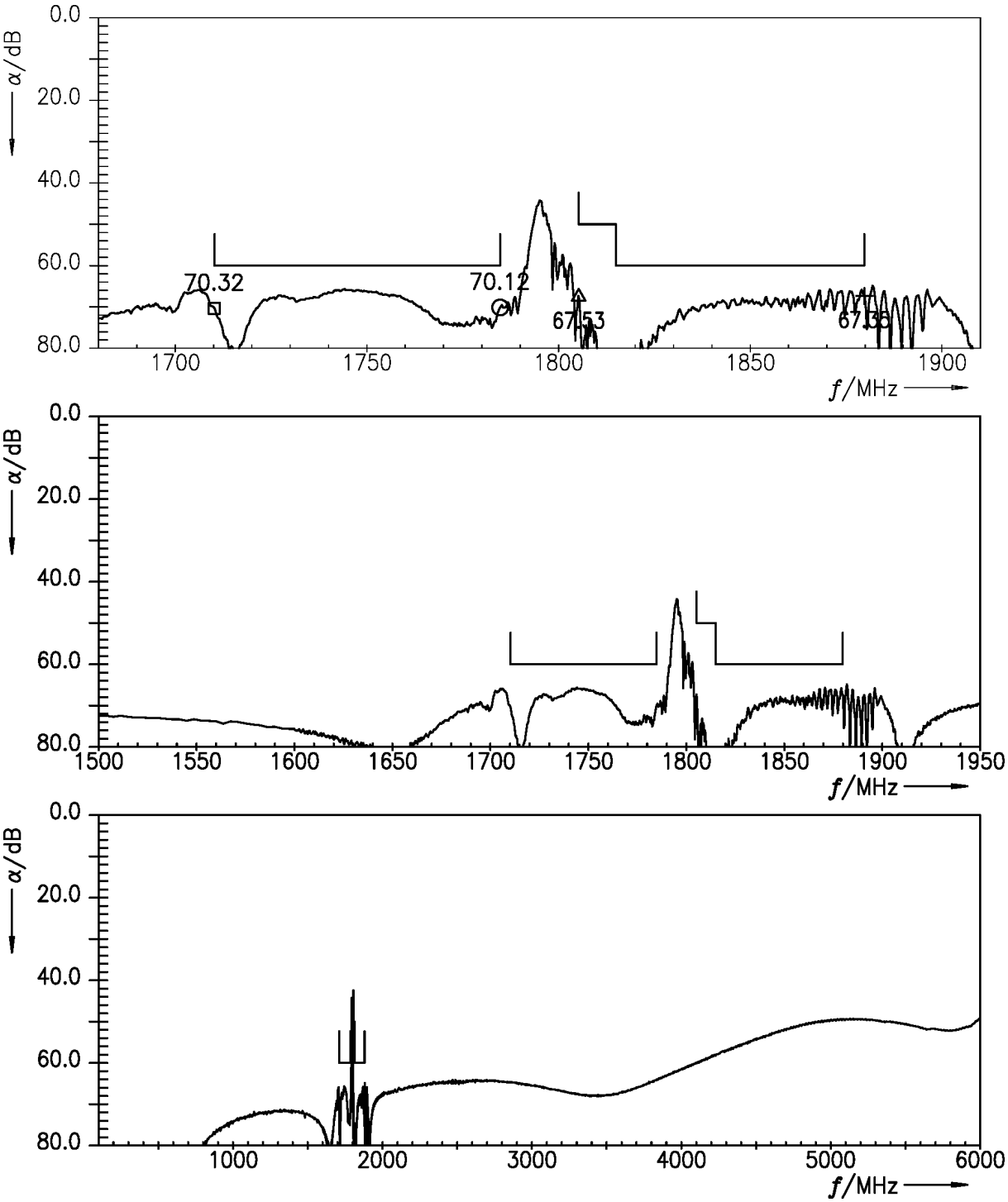

Figure 6: Isolation TX – RX.

9 Reflection coefficients

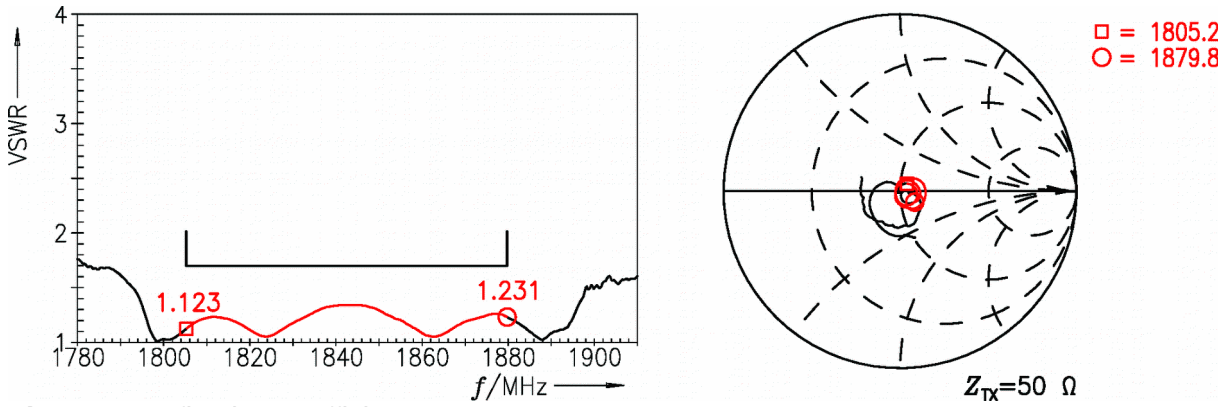

Figure 7: Reflection coefficient at TX port.

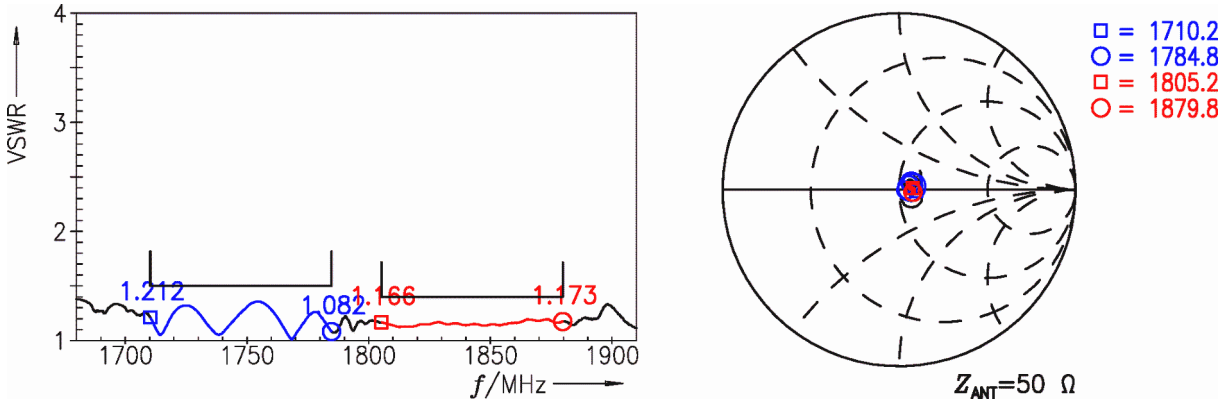

Figure 8: Reflection coefficient at ANT port.

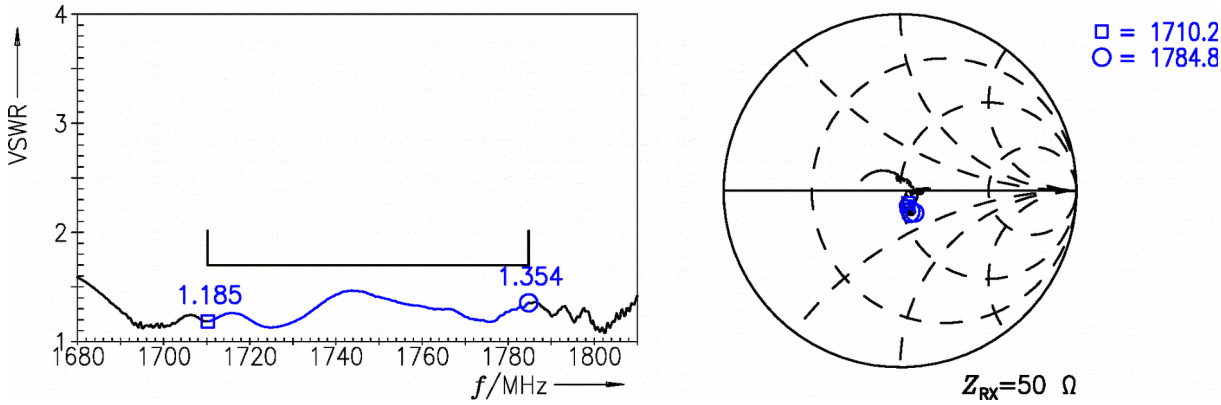

Figure 9: Reflection coefficient at RX port.

10 EVMs

10.1 TX – ANT

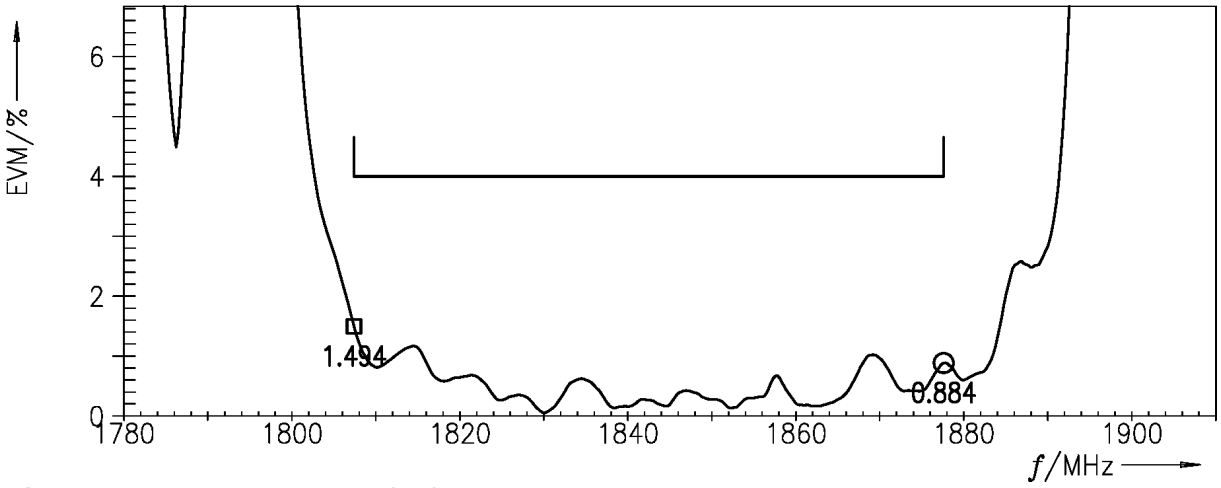

Figure 10: Error vector magnitude TX – ANT.

10.2 ANT – RX

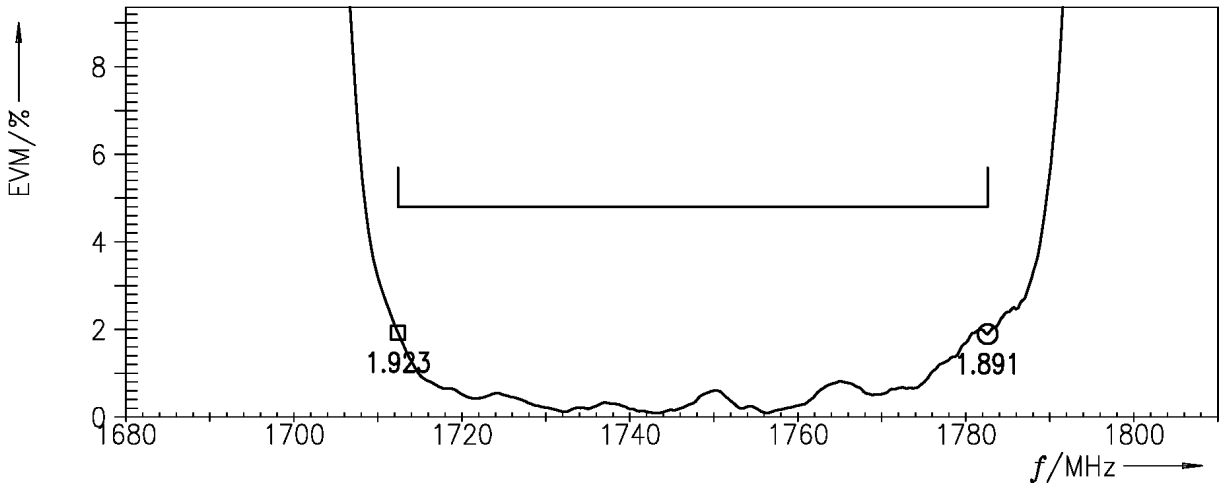

Figure 11: Error vector magnitude ANT – RX.

11 Packing material

11.1 Tape

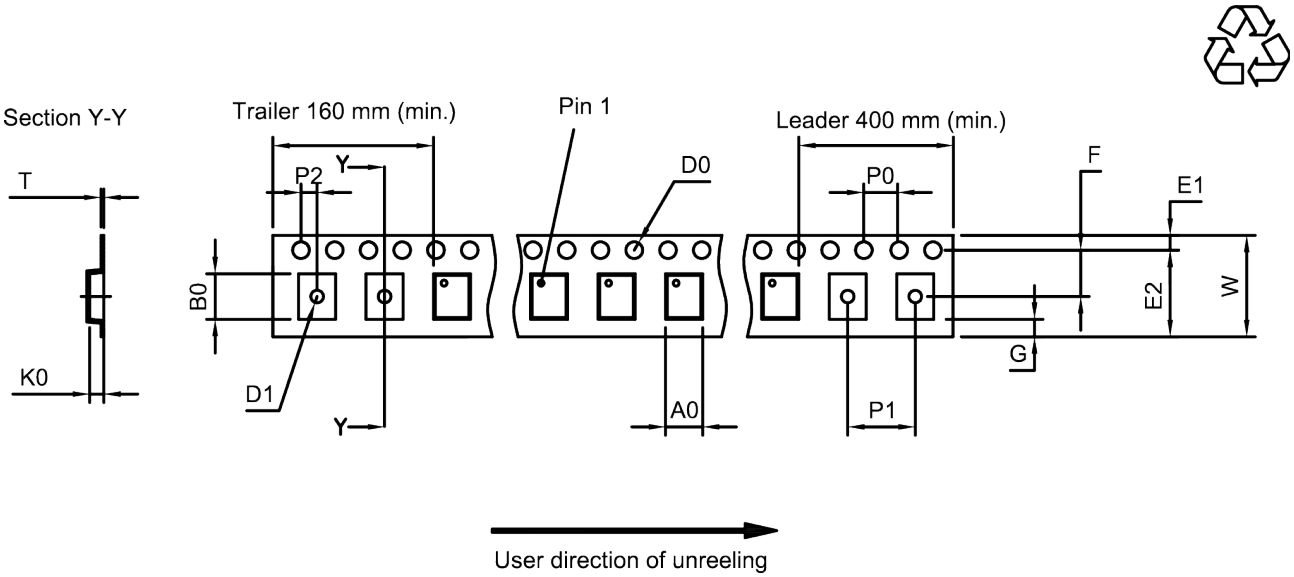

Figure 12: Drawing of tape (first-angle projection) with tape dimensions according to Table 1.

A_0	8.4±0.05 mm
B_0	8.4±0.05 mm
D_0	1.5+0.1/−0 mm
D_1	1.5 mm (min.)
E_1	1.75±0.1 mm

E_2	14.25 mm (min.)
F	7.5±0.1 mm
G	0.75 mm (min.)
K_0	1.3±0.1 mm
P_0	4.0±0.1 mm

P_1	12.0±0.1 mm
P_2	2.0±0.1 mm
T	0.3±0.05 mm
W	16.0+0.3/−0.1 mm

Table 1: Tape dimensions.

11.2 Reel with diameter of 330 mm

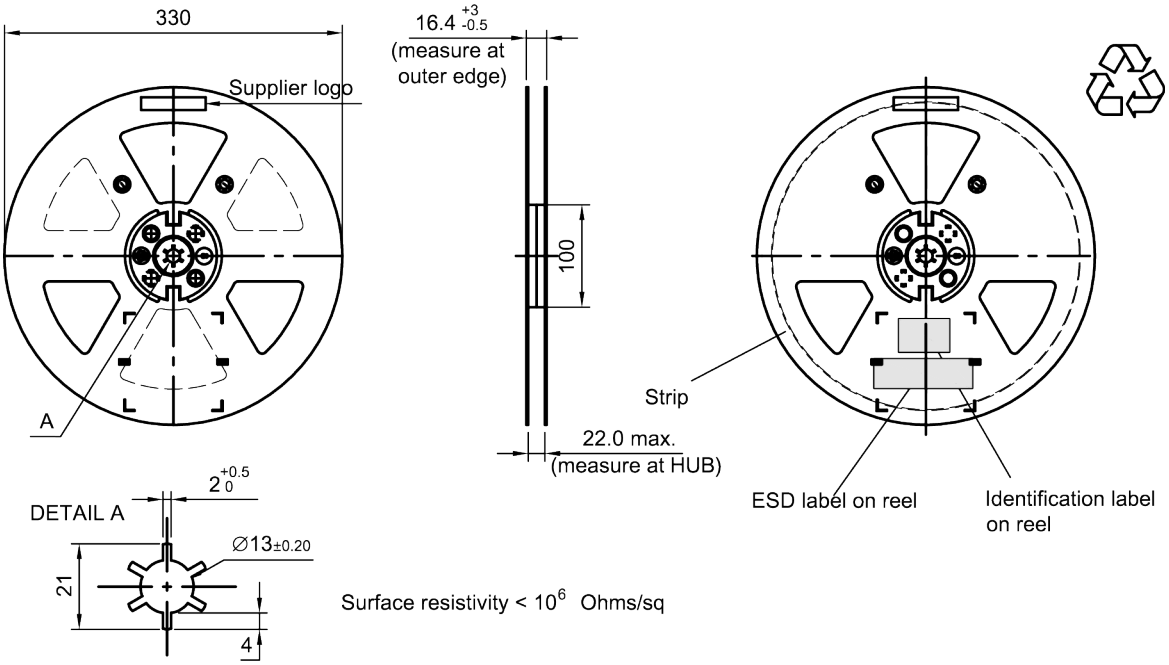

Figure 13: Drawing of reel (first-angle projection) with diameter of 330 mm.

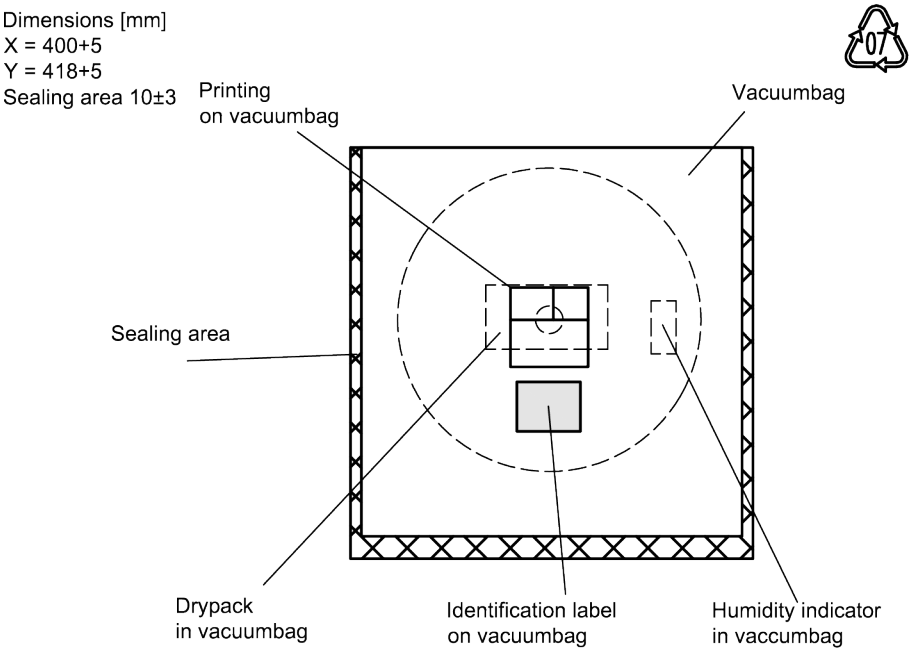

Figure 14: Drawing of moisture barrier bag (MBB) for reel with diameter of 330 mm.

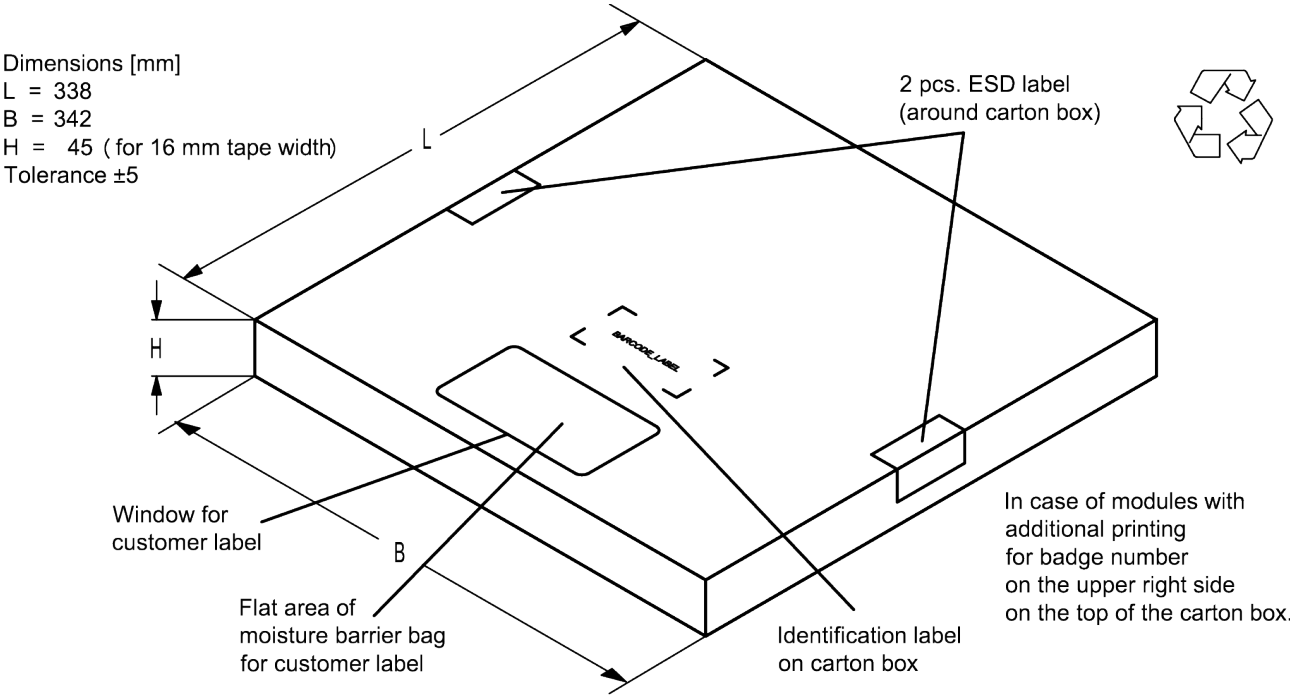

Figure 15: Drawing of folding box for reel with diameter of 330 mm.

12 Marking

Products are marked with tracking number (5 or 8 characters), type designator (5 characters), as well as production location and date code (4 characters). The marking corresponds to one of the following schemes:

XXXXX	5-character tracking number
XXXXX	5-character type designator
M5C6	1-character location code + 3-character date code (example)

Table 2: Marking for 5-character tracking number (standard).

XXXXXXXX	8-character tracking number
XXXXX	5-character type designator
M5C6	1-character location code + 3-character date code (example)

Table 3: Marking for 8-character tracking number.

???	
XXXXXXXX	8-character tracking number
XXXXX	5-character type designator
M5C6	1-character location code + 3-character date code (example)

Table 4: Marking for 8-character tracking number with 4 lines.

- Tracking number: *t.b.d.*

- Type designator: The 5-character type designator of the ordering code is used for the marking.

  Example: B3xxxx**D1234**xxxx

- Production-location and date code: The production-location is encoded in the first character according to Table 5. The production date code is encoded in the last three characters according to Table 6.

Code:	M or no letter	J	C	H
Location:	Munich	Singapore	Wuxi	SAE, Hong Kong

Table 5: Production location code.

1st digit (day)					
Day	Code	Day	Code	Day	Code
1	1	11	A	21	M
2	2	12	B	22	N
3	3	13	C	23	P
4	4	14	D	24	R
5	5	15	E	25	S
6	6	16	F	26	T
7	7	17	H	27	U
8	8	18	J	28	V
9	9	19	K	29	W
10	0	20	L	30	X
				31	Z

2nd digit (year)			
Year	Code	Year	Code
2010	A	2022	P
2011	B	2023	R
2012	C	2024	S
2013	D	2025	T
2014	E	2026	U
2015	F	2027	V
2016	H	2028	W
2017	J	2029	X
2018	K	2030	Z
2019	L	2031	A
2020	M	2032	B
2021	N	and so on	

3rd digit (month)			
Month	Code	Month	Code
Jan	1	Jul	7
Feb	2	Aug	8
Mar	3	Sep	9
Apr	4	Oct	0
May	5	Nov	N
Jun	6	Dec	D

Table 6: Production date code.

Example of how to decode production location and date code:

Code: **M 5 C 6**

Location: M → Munich
Day: 5 → 5th
Year: C → 2012
Month: 6 → June

13 Soldering profile

The recommended soldering process is in accordance with IEC 60068-2-58 – 3rd edit and IPC/JEDEC J-STD-020B.

ramp rate	≤ 3 K/s
preheat	125 °C to 220 °C, 150 s to 210 s, 0.4 K/s to 1.0 K/s
T > 220 °C	30 s to 70 s
T > 230 °C	min. 10 s
T > 245 °C	max. 20 s
T ≥ 255 °C	–
peak temperature T_{peak}	250 °C +0/-5 °C
wetting temperature T_{min}	230 °C +5/-0 °C for 10 s ± 1 s
cooling rate	≤ 3 K/s
soldering temperature T	measured at solder pads

Table 7: Characteristics of recommended soldering profile for lead-free solder (Sn95.5Ag3.8Cu0.7).

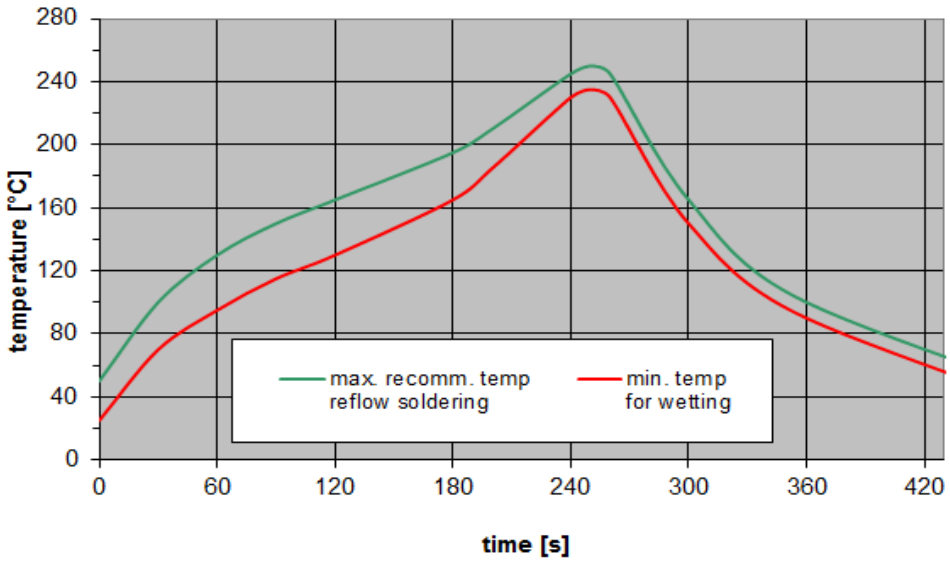

Figure 16: Recommended reflow profile for convection and infrared soldering – lead-free solder.

14 Annotations

14.1 Matching coils

See TDK inductor pdf-catalog http://www.tdk.co.jp/tefe02/coil.htm#aname1 and Data Library for circuit simulation http://www.tdk.co.jp/etvcl/index.htm.

14.2 RoHS compatibility

ROHS-compatible means that products are compatible with the requirements according to Art. 4 (substance restrictions) of Directive 2011/65/EU of the European Parliament and of the Council of June 8th, 2011, on the restriction of the use of certain hazardous substances in electrical and electronic equipment ("Directive") with due regard to the application of exemptions as per Annex III of the Directive in certain cases.

14.3 Scattering parameters (S-parameters)

The pin/port assignment is available in the headers of the S-parameter files. Please contact your local RF360 sales office.

14.4 Ordering codes and packing units

Ordering code	Packing unit
B39182D7906D310	3000 pcs

Table 8: Ordering codes and packing units.

15 Cautions and warnings

15.1 Display of ordering codes for RF360 products

The ordering code for one and the same product can be represented differently in data sheets, data books, other publications and the website of RF360, or in order-related documents such as shipping notes, order confirmations and product labels. The varying representations of the ordering codes are due to different processes employed and do not affect the specifications of the respective products. Detailed information can be found on the Internet under www.rf360jv.com/orderingcodes.

15.2 Material information

Due to technical requirements components may contain dangerous substances. For information on the type in question please also contact one of our sales offices.

For information on recycling of tapes and reels please contact one of our sales offices.

15.3 Moldability

Before using in overmolding environment, please contact your local RF360 sales office.

15.4 Package information

Landing area

The printed circuit board (PCB) land pattern (landing area) shown is based on RF360 internal development and empirical data and illustrated for example purposes, only. As customers' SMD assembly processes may have a plenty of variants and influence factors which are not under control or knowledge of RF360, additional careful process development on customer side is necessary and strongly recommended in order to achieve best soldering results tailored to the particular customer needs.

Dimensions

Unless otherwise specified all dimensions are understood using unit millimeter (mm).

Projection method

Unless otherwise specified first-angle projection is applied.

16 Important notes

The following applies to all products named in this publication:

1. Some parts of this publication contain **statements about the suitability of our products for certain areas of application**. These statements are based on our knowledge of typical requirements that are often placed on our products in the areas of application concerned. We nevertheless expressly point out **that such statements cannot be regarded as binding statements about the suitability of our products for a particular customer application.** As a rule, RF360 Europe GmbH and its affiliates are either unfamiliar with individual customer applications or less familiar with them than the customers themselves. For these reasons, it is always ultimately incumbent on the customer to check and decide whether an RF360 product with the properties described in the product specification is suitable for use in a particular customer application.
2. We also point out that **in individual cases, a malfunction of electronic components or failure before the end of their usual service life cannot be completely ruled out in the current state of the art, even if they are operated as specified.** In customer applications requiring a very high level of operational safety and especially in customer applications in which the malfunction or failure of an electronic component could endanger human life or health (e.g. in accident prevention or life-saving systems), it must therefore be ensured by means of suitable design of the customer application or other action taken by the customer (e.g. installation of protective circuitry or redundancy) that no injury or damage is sustained by third parties in the event of malfunction or failure of an electronic component.
3. **The warnings, cautions and product-specific notes must be observed.**
4. In order to satisfy certain technical requirements, **some of the products described in this publication may contain substances subject to restrictions in certain jurisdictions (e.g. because they are classed as hazardous)**. Useful information on this will be found in our Material Data Sheets on the Internet (www.rf360jv.com/material). Should you have any more detailed questions, please contact our sales offices.
5. We constantly strive to improve our products. Consequently, **the products described in this publication may change from time to time**. The same is true of the corresponding product specifications. Please check therefore to what extent product descriptions and specifications contained in this publication are still applicable before or when you place an order. We also **reserve the right to discontinue production and delivery of products**. Consequently, we cannot guarantee that all products named in this publication will always be available.
   The aforementioned does not apply in the case of individual agreements deviating from the foregoing for customer-specific products.

单击下面可查看定价，库存，交付和生命周期等信息

>>Qualcomm-RF360